

IN THE SPECIFICATION:

Please amend the paragraph beginning at page 3, line 16 as follows:

The upper substrate 101 is press-bonded to the lower substrate 102. The spacers 115 function as an adhesive. An interval between the upper and lower substrates is regulated by the height of the spacer 115. The height of the Au bump 114 is slightly larger than that of the spacer 115. Therefore, when the upper and lower substrates are bonded to each other, the electrode pad 108 contacts the Au bump 114 and is pushed upwards together with the portion 106a. ~~[[An]]~~ A tensile force of the portion 106a constantly electrically connects the Au bump 114 to the electrode pad 108. As a result, the upper electrode 107 is conducted to the second electrode pad 113. The lower electrode 111 is conducted to the first electrode pad 112.

Please amend the paragraph beginning at page 8, line 6 as follows:

FIG. 2 is a sectional view of the electrostatic driving device taken along ~~a-II-II~~ sectional line II-II of FIG. 1C;

Please amend the paragraph beginning at page 8, line 18 as follows:

FIG. 5 is a sectional view of the electrostatic driving device taken along ~~a-V-V~~ sectional line V-V of FIG. 4B;

Please amend the paragraph beginning at page 9, line 3 as follows:

FIG. 8 is a sectional view of the electrostatic driving device taken along ~~a-VIII-VIII~~ sectional line VIII-VIII of FIG. 7C;

Please amend the paragraph beginning at page 9, line 18 as follows:

First, the electrostatic driving device of a first embodiment of the present invention will be described with reference to FIGS. 1A, 1B, 1C, and 2. The electrostatic driving device comprises a flexible thin film 4, a holding member 3, which holds the flexible thin film 4 and allows the flexible thin film 4 to deform, and a base 7, which faces the holding member 3. FIG. 1A is a plan view of the holding member 3, and the surface positioned opposite to the surface that faces the base 7 is shown. FIG. 1B is a plan view of the base 7. A surface 7a facing the holding member 3 is shown. FIG. 1C is a plan view of the electrostatic driving device as viewed from a holding member 3 side. FIG. 2 is a sectional view of the electrostatic driving device taken along ~~a-H-H~~ sectional line II-II of FIG. 1C.

Please amend the paragraph beginning at page 19, line 23 as follows:

The electrostatic driving device of a second embodiment of the present invention will now be described with reference to FIGS. 4A, 4B, and 5. Substantially the same constituting members as those of the first embodiment are denoted with the same reference numerals and a detailed description thereof is omitted. The electrostatic driving device of the present embodiment has substantially the same holding member 3, flexible thin film 4, conductive film 5, and reflective film 6 as those of the first embodiment. The electrostatic driving device has a base 15, which faces the holding member 3. FIG. 4A is a plan view of the base 15, and a surface 15a facing the holding member 3 is shown. FIG. 4B is a plan view of the electrostatic driving device as viewed from the holding member 3 side. FIG. 5 is a sectional view of the electrostatic driving device taken along ~~a-V-V~~ sectional line V-V of FIG. 4B. The base 15 has a flat plate like shape, and is formed of silicon. The base-side facing electrode 8 facing the film-side facing electrode 5a and formed of a circular

aluminum film is disposed on the surface 15a of the base 15. A conductive electrode pad 18 and dummy pads 20 and 21 are fixed to the surface 15a. The pads 18, 20, and 21 surround the base-side facing electrode 8. The pads 18, 20, and 21 have sheet shapes and equal thickness. The external electrode 9 and external electrode 11 are fixed to the surface 15a in the same manner as in the first embodiment. The base-side facing electrode 8 is connected to the external electrode 9 through the wiring 9a, and the electrode pad 18 is connected to the external electrode 11 through the wiring 11a. The external electrode 9 and external electrode 11 are disposed on the surface 15a at positions that are not covered with the holding member 3.

Please amend the paragraph beginning at page 25, line 11 as follows:

The electrostatic driving device of a third embodiment of the present invention will now be described with reference to FIGS. 7A, 7B, 7C, and 8. Substantially the same constituting members as those of the first embodiment are denoted with the same reference numerals and [[the]] a detailed description thereof is omitted. The electrostatic driving device has substantially the same holding member 3, flexible thin film 4, conductive film 5, and reflective film 6 as those of the first embodiment. The electrostatic driving device includes a base 24, which faces the holding member 3. The electrostatic driving device includes the bonding spacer member for bonding the holding member 3 and base 24. The bonding spacer member is held between the holding member 3 and base 24. The bonding spacer member includes a bonding member 36, which contains silicone adhesive, and the rigid members 14, which are substantially the same number of as those of the first embodiment. FIGS. 7A and 7B are plan views of the base 24, and a surface 24a facing the holding member 3 is shown. FIG. 7A does not show the bonding spacer member, and FIG. 7B shows the bonding spacer

member. FIG. 7C is a plan view of the electrostatic driving device as viewed from the holding member 3 side. FIG. 8 is a sectional view of the electrostatic driving device taken along a ~~VII-VII~~ sectional line VIII-VIII of FIG. 7C. The base 24 has a flat plate like shape, and is formed of silicon. The base-side facing electrode 8 facing the film-side facing electrode 5a is disposed on the surface 24a of the base 24. A conductive electrode pad 27, and dummy pads 29, 30, and 31 are fixed to the surface 24a. The dummy pads 29, 30, and 31 surround the base-side facing electrode 8. The pads 27, 29, 30, and 31 have the sheet shapes and the equal thickness. The external electrode 9 and external electrode 11 are fixed to the surface 24a. The base-side facing electrode 8 is connected to the external electrode 9 through the wiring 9a, and the electrode pad 27 is connected to the external electrode 11 through the wiring 11a. The external electrode 9 and external electrode 11 are disposed on the surface 24a at positions that are not covered with the holding member 3.

Please amend the paragraph beginning at page 25, line 11 as follows:

The protrusion 32 is surrounded with a conductive adhesive 34. The conductive adhesive 34 is held between the tip of the protrusion 32 and the conductive film 5 to ~~conducted~~ conduct the film-side facing electrode 5a to the external electrode 11.